

80N40DG-VB TO262 Datasheet N-Channel 40-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY			
V _{(BR)DSS} (V)	r _{DS(on)} (∧)	I _D (A)	Q _g (Typ.)
40	0.005 at V _{GS} = 10 V	100	95

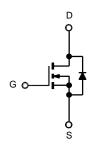
FEATURES

- · Trench Power MOSFET
- 175 °C Junction Temperature
- · High Threshold Voltage at High Temperature









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS TC=	= 25 °C, unless other	wise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	40	V	
Gate-Source Voltage		V_{GS}	20		
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C	- I _D	110		
	T _C = 125 °C		70		
Pulsed Drain Current		I _{DM}	300	A	
Avalanche Current		I _{AR}	50		
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	125	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	В	150 ^b	144	
	T _A = 25 °C ^c	- P _D	3.75	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	40	°C/W	
Junction-to-Case		R_{thJC}	1]	

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				'	'		
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	40			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.0	2.0	4.0		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$			1		
	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 125 °C			50	μA	
		V _{DS} = 40 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
Drain-Source On-State Resistance ^a		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.005			
	r _{DS(on)}	V _{GS} = 10 V, I _D = 15 A, T _J = 125 °C		0.008		^	
	, ,	V _{GS} = 10 V, I _D = 15 A, T _J = 175 °C		0.0106			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A	20	50		S	
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		3200		pF	
Output Capacitance	C _{oss}			600			
Reverse Transfer Capacitance	C _{rss}			320			
Total Gate Charge ^c	Qg			95		nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		37			
Gate-Drain Charge ^c	Q _{gd}			21			
Gate Resistance	R _g	f = 1.0 MHz		1.7		٨	
Turn-On Delay Time ^c	t _{d(on)}			20	30	ns	
Rise Time ^c	t _r	$V_{DD} = 20 \text{ V}, R_L = 0.4 \land$ $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \land$		95	145		
Turn-Off Delay Time ^c	t _{d(off)}			50	75		
Fall Time ^c	t _f			12	20		
Source-Drain Diode Ratings and Cha	racteristics T	_C = 25 °C ^b					
Continuous Current	Is				100	^	
Pulsed Current	I _{SM}				300	A	
Forward Voltage ^a	V _{SD}	$I_F = 30 \text{ A}, V_{GS} = 0 \text{ V}$		0.90	1.50	V	
Reverse Recovery Time	t _{rr}	I _F = 30 A, di/dt = 100 A/µs		40	60	ns	

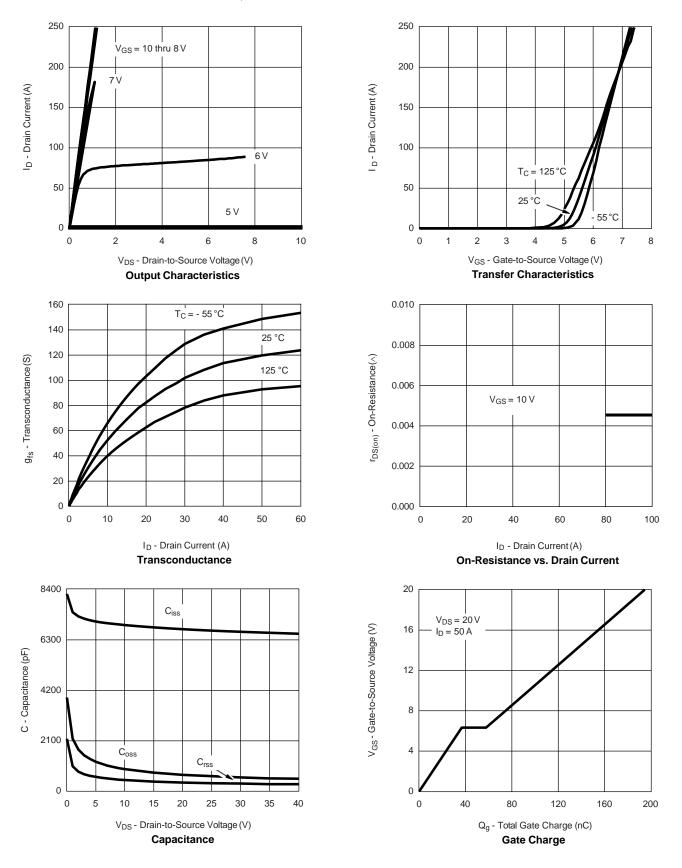
Notes:

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- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing. c. Independent of operating temperature.

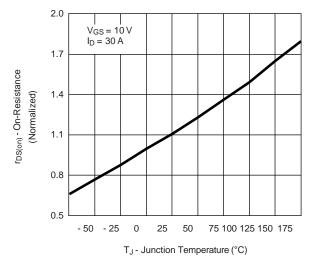


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

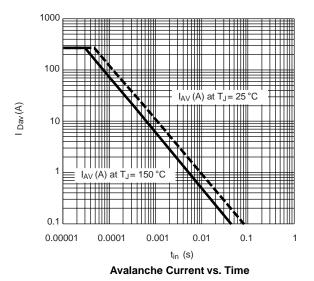


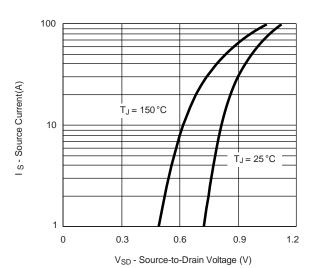


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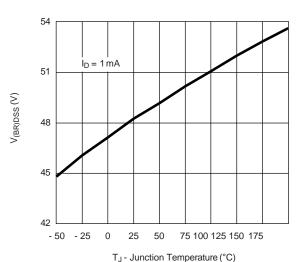


On-Resistance vs. Junction Temperature





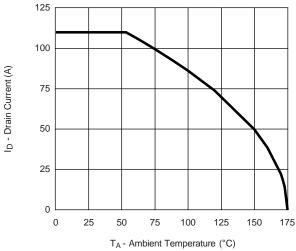
Source-Drain Diode Forward Voltage



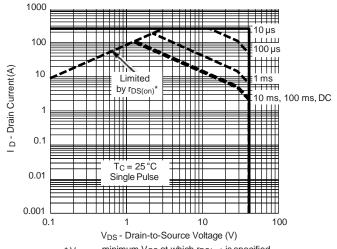
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS

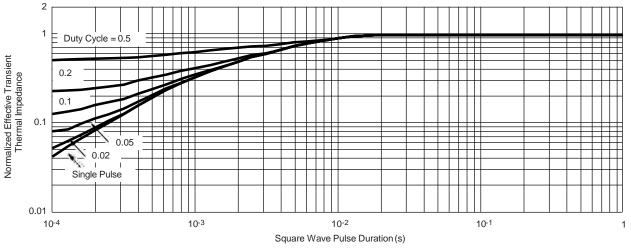


Maximum Avalanche and Drain Current vs. Case Temperature



* $V_{GS} \,>\,$ minimum V_{GS} at which $r_{DS(on)}$ is specified





Normalized Thermal Transient Impedance, Junction-to-Case



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